TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (High speed U-MOSIII)

# ТРС8009-Н

High Speed and High Efficiency DC-DC Converters Notebook PC Applications Portable Equipment Applications

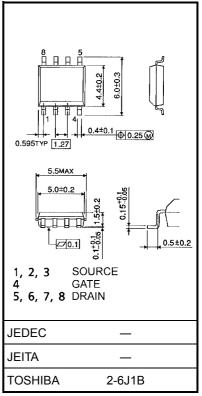
- Small footprint due to small and thin package
- High speed switching
- Small gate charge: Qg = 29 nC (typ.)
- Low drain-source ON resistance:  $R_{DS}$  (ON) = 8 m $\Omega$  (typ.)
- High forward transfer admittance:  $|\,Y_{\rm fs}\,|$  = 16 S (typ.)
- Low leakage current:  $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 30 \ V)$
- Enhancement mode:  $V_{th}$  = 1.1 to 2.3 V (V\_{DS} = 10 V,  $I_{D}$  = 1 mA)

#### Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	30	V	
Drain-gate voltage (F	k <sub>GS</sub> = 20 kΩ)	V <sub>DGR</sub>	30	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	۱ <sub>D</sub>	13	А	
Drain current	Pulse (Note 1)	I <sub>DP</sub>	52	ζ.	
Drain power dissipati	on (t = 10 s) (Note 2a)	PD	1.9	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	PD	1.0	W	
Single pulse avalanc	ne energy (Note 3)	E <sub>AS</sub>	219	mJ	
Avalanche current		I <sub>AR</sub>	13	А	
Repetitive avalanche (	energy Note 2a) (Note 4)	E <sub>AR</sub>	0.19	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature	range	T <sub>stg</sub>	–55 to 150	°C	

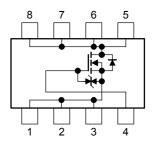
Note: (Note 1), (Note 2), (Note 3), (Note 4) Please see next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.080 g (typ.)

#### **Circuit Configuration**



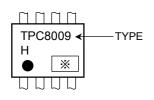
Unit: mm

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## **Thermal Characteristics**

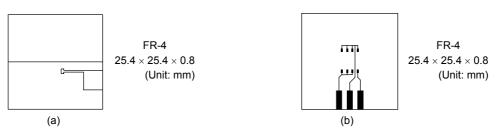
Characteristics	Symbol	Max	Unit	
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R <sub>th (ch-a)</sub>	65.8	°C/W	
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R <sub>th (ch-a)</sub>	125	°C/W	

## Marking (Note 5)



Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)



(b) Device mounted on a glass-epoxy board (b)

- Note 3:  $V_{DD} = 24 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$  (initial), L = 1.0 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = 13 A
- Note 4: Repetitive rating; pulse width limited by max channel temperature.
- Note 5: on lower left of the marking indicates Pin 1.

% shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

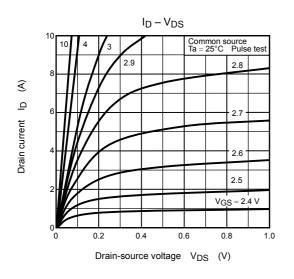
Electrical Characteristics (Ta = 25°C)

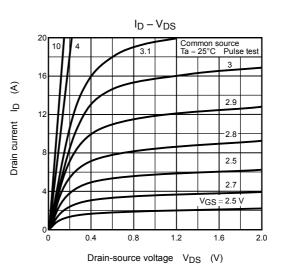
Ch	aracteristics	Symbol	Test Condition	Min Typ. Max		Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	$V_{GS}=\pm 16~V,~V_{DS}=0~V$	_		±10	μA
Drain cut-OFF cu	urrent	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			10	μA
Drain-source bre	akdown voltage	V (BR) DSS	$I_{D} = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	30		_	v
		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	15	$\begin{array}{cccccccccccccccccccccccccccccccccccc$		v
Gate threshold v	oltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	1.1	_	2.3	V
	Irogiotanog	Provin	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 6.5 \text{ A}$	_	11	15	
		R <sub>DS</sub> (ON)	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 6.5 \text{ A}$		8	10	mΩ
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 6.5 \text{ A}$	8	16		S
Input capacitance	Input capacitance		V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		1460		pF
Reverse transfer capacitance		C <sub>rss</sub>			250		
Output capacitance		C <sub>oss</sub>		_	600		
Output capacitanc	Rise time	tr	$V_{GS} \stackrel{10}{}_{0}V \prod I_{D} = 6.5 \text{ A}$	_	5	_	- ns
	Turn-ON time	t <sub>on</sub>			13	_	
	Fall time	t <sub>f</sub>			12	_	
	Turn-OFF time	t <sub>off</sub>	$V_{DD}\simeq 15~V \label{eq:VDD}$ Duty $\leq$ 1%, $t_W=10~\mu s$		37	_	
Total gate charge	Total gate charge		$V_{DD}\simeq 24~V,~V_{GS}=10~V,~I_{D}=13~A$		29		
(gate-source plus	s gate-drain)	Qg	$V_{DD}\simeq 24~V,~V_{GS}=5~V,~I_{D}=13~A$		— 16 —		
Gate-source charge 1		Q <sub>gs1</sub>			4.2		nC
Gate-drain ("miller") charge		Q <sub>gd</sub>	$V_{DD} \simeq 24$ V, $V_{GS} = 10$ V, $I_D = 13$ A		7.3	_	
Gate switch charge		Q <sub>SW</sub>			9.1	_	

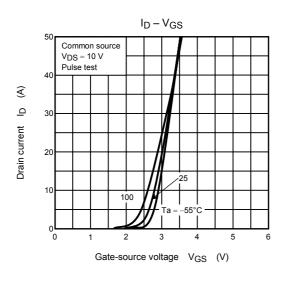
## Source-Drain Ratings and Characteristics (Ta = 25°C)

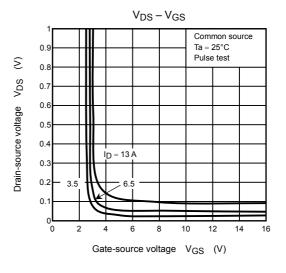
Characteri	stics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse	(Note 1)	I <sub>DRP</sub>	—	_	_	52	А
Forward voltage (diode)			V <sub>DSF</sub>	I <sub>DR</sub> = 13 A, V <sub>GS</sub> = 0 V	_	_	-1.2	V

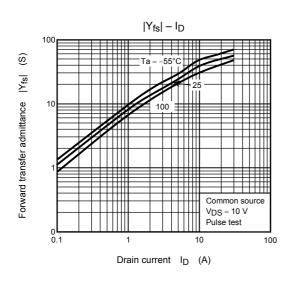
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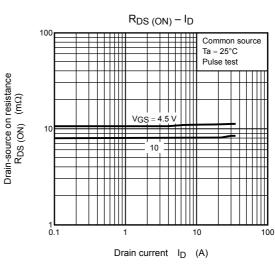




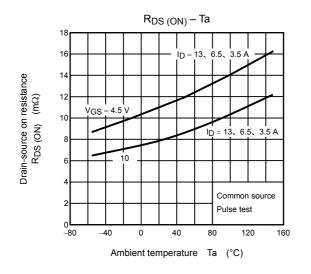


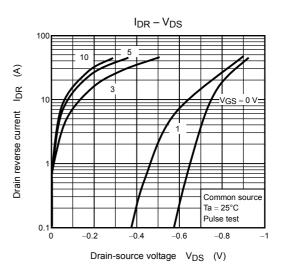


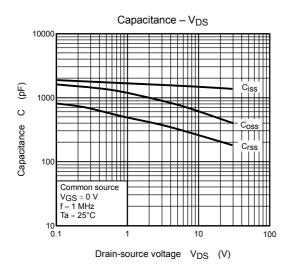


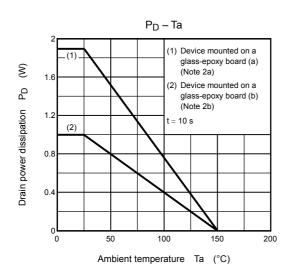


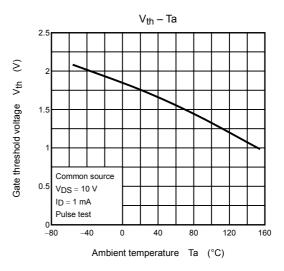
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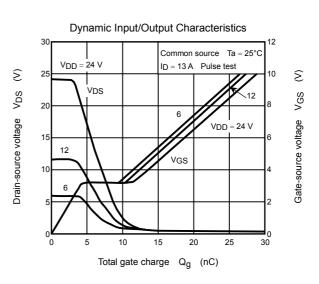


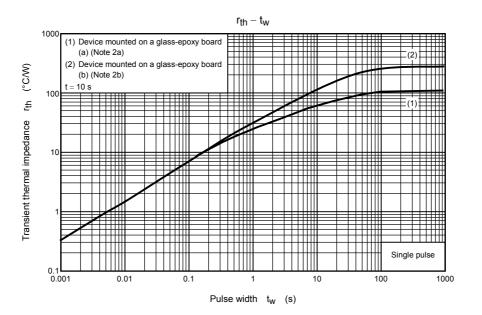




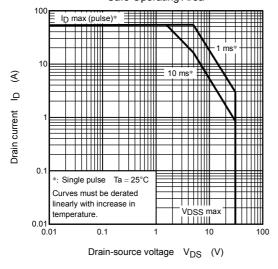








Safe Operating Area



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